System Information:

- **Instrument Provider: Oxford Instruments**
- **Gases Available: SiH_4, NH_3,N_2O,Ar, He, H_2, N_2, CF_4**
- **Films Deposited: SiN_x, SiO_x, SiO_xN_y, a-Si**
- **Wafer Dimensions Allowed : Small pieces, 125 x 125 mm, and 156 x 156 mm**

TRAINING PROCESS:

- **Get approval from your Guide/Faculty Advisor**
- **Contact the System Owner**
- **You need to attend at least two etch sessions with any authorized user**
- **After that you need to attend one or two hands-on session**
- **A test will be taken after that and authorization will be given if cleared, else you need to go for more training sessions before next test**

SAFETY HAZARDS & PRECAUTIONS:

- **Ensure that the Chiller is turned ON**
- **Ensure that the gases are turned ON at the service end by facility team members**
- **Ensure that the exhaust blower is ON before starting the tool.**
- **Ensure that the scrubber is turned ON before starting the tool.**
- **Always start the tool after consulting the facility team members.**